


Standardized Information for Process/Product Change Notification (PCN)

1. PCN basic data		
1.1 Company	 TAIWAN SEMICONDUCTOR	TAIWAN SEMICONDUCTOR CO.,LTD
1.2 PCN No.	PCN22005	
1.3 Title of PCN	SSD products bonding wire and wafer diameter change	
1.4 Product Category	Active Components - Discrete Components	
1.5 Issue date	2022/05/03	
1.6 PCN revision history (optional)	1.7 Issue date of previous revision (optional)	1.8 Delta to previous revision (optional)

Form provided by ZVEI - Revision 5.0

2. PCN Team		
2.1 Contact supplier		
2.1.1 Name	Delia Chang	
2.1.2 Phone	+886-3-928-5017 Ext:315	
2.1.3 Email	delia.chang@mail.ts.com.tw	
2.2 Team supplier (optional)		
2.2.1 Name (optional)	2.2.2 Phone (optional)	2.2.3 Email (optional)
Jen Peralta	+886 8913 1588 ext. 2406	jen.peralta@mail.ts.com.tw

3. Changes			
No.	3.0 Ident	3.1 Category	3.2 Type of change
#1	SEM-PW-02	PROCESS - WAFER PRODUCTION	New wafer diameter
#2	SEM-PA-08	PROCESS - ASSEMBLY	Change of wire bonding
#3	SEM-PA-16	PROCESS - ASSEMBLY	Change of direct material supplier

4. Description of change		
	Old	New
Change #1	Wafer diameter: 5"	Wafer diameter: 6"
Change #2	wire : Au	wire : Cu
Change #3		
4.1 Anticipated impact on form, fit, function, reliability or processability?	There is no impact on the form, fit, function, reliability or process ability. This change will guarantee Taiwan Semiconductor commitment on customer service and satisfaction through continuous improvement.	
4.2 Reference parts with customer number (optional)		

